Materials Declaration

Package	LQFP
Body Size	10 X 10
LeadCount	44
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.06 E-02	36990
SiO2 Filler	86	1.13 E-01	397645
Phenol Resin	5	6.59 E-03	23119
Antimony_Sb2O3	0.4	5.28 E-04	1850
Brominated Resin	0.4	5.28 E-04	1850
Carbon Black	0.2	2.64 E-04	925

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	9.48 E-02	332535
Ni	3	2.96 E-03	10370
Si	0.65	6.41 E-04	2247
Mg	0.15	1.48 E-04	519

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.00 E-03	7012

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	9.15 E-03	32079

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.20 E-03	4191

Chip

	% of Chip	Weight (g)	PPM
Si	100	3.86 E-02	135445

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	9.81 E-04	3438
Ag Filler	74	2.79 E-03	9786

Package Totals

Weight (g)	PPM
2.85 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

7/6/04

Materials Declaration

Package	LQFP
Body Size	10 X 10
LeadCount	44
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	1.06 E-02	36990
SiO2 Filler	86	1.13 E-01	397645
Phenol Resin	5	6.59 E-03	23119
Antimony_Sb2O3	0.4	5.28 E-04	1850
Brominated Resin	0.4	5.28 E-04	1850
Carbon Black	0.2	2.64 E-04	925

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	9.48 E-02	332535
Ni	3	2.96 E-03	10370
Si	0.65	6.41 E-04	2247
Mg	0.15	1.48 E-04	519

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	2.00 E-03	7012

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	7.78 E-03	27267
Pb	15	1.37 E-03	4812

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	1.20 E-03	4191

Chip

	% of Chip	Weight (g)	PPM
Si	100	3.86 E-02	135445

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	9.81 E-04	3438
Ag Filler	74	2.79 E-03	9786

Package Totals

Weight (g)	PPM
2.85 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2.0	EPA method #3052 (ICPAES)
Cd	<2.0	BS EN 1122:2001B (ICP AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS in-house Method by GC/MS
PBDE	ND	SGS in-house Method by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	<5.0	EPA method 7196A & EPA 3060A

STS-ST-A

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